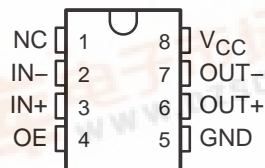


## DIFFERENTIAL COMPARATOR

SLCS002D – JUNE 1983 – REVISED AUGUST 2003

- Operates From a Single 5-V Supply
- 0-V to 5.5-V Common-Mode Input Voltage Range
- Self-Biased Inputs
- Complementary 3-State Outputs
- Enable Capability
- Hysteresis . . . 5 mV Typ
- Response Times . . . 25 ns Typ

### D, P, PS, OR PW PACKAGE (TOP VIEW)



NC – No internal connection

### description/ordering information

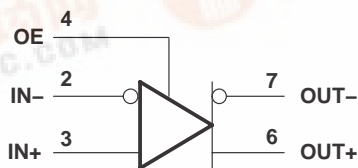
The TL712 is a high-speed comparator fabricated with bipolar Schottky process technology. The circuit has differential analog inputs and complementary 3-state TTL-compatible logic outputs with symmetrical switching characteristics. When the output enable (OE) is low, both outputs are in the high-impedance state. This device operates from a single 5-V supply and is useful as a disk memory read-chain data comparator.

### ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (P)	Tube of 50	TL712CP	TL712CP
		Tube of 75	TL712CD	TL712C
	SOIC (D)	Reel of 2500	TL712CDR	
		Reel of 2000	TL712CPSR	T712
	TSSOP (PW)	Tube of 150	TL712CPW	T712
		Reel of 2000	TL712CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

### symbol (positive logic)

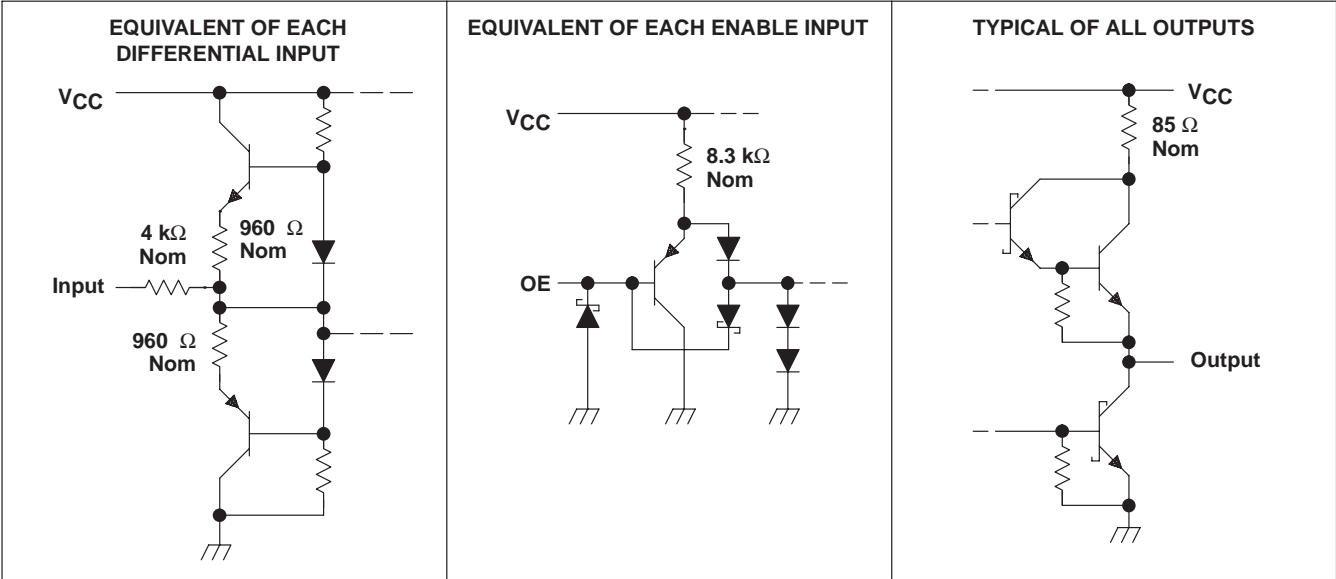


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# TL712 DIFFERENTIAL COMPARATOR

SLCS002D – JUNE 1983 – REVISED AUGUST 2003

## schematics of inputs and outputs



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Differential input voltage, $V_{ID}$ (see Note 2)	$\pm 25$ V
Input voltage, $V_I$ , any differential input	$\pm 25$ V
Output enable voltage	7 V
Low-level output current, $I_{OL}$	50 mA
Package thermal impedance, $\theta_{JA}$ (see Notes 3 and 4):	
D package	97°C/W
P package	85°C/W
PS package	95°C/W
PW package	149°C/W
Operating virtual junction temperature, $T_J$	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the “recommended operating conditions” section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to the network ground.
  2. Differential voltage values are at  $IN+$  with respect to  $IN-$ .
  3. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  4. The package thermal impedance is calculated in accordance with JESD 51-7.

# TL712 DIFFERENTIAL COMPARATOR

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## recommended operating conditions

	MIN	NOM	MAX	UNIT
V <sub>CC</sub> Supply voltage	4.75	5	5.25	V
V <sub>IC</sub> Common-mode input voltage	0		5.5	V
I <sub>OH</sub> High-level output current			–1	mA
I <sub>OL</sub> Low-level output current			16	mA
T <sub>A</sub> Operating free-air temperature	0		70	°C

## electrical characteristics at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>T</sub> Threshold voltage (V <sub>T+</sub> and V <sub>T–</sub> )	V <sub>ICR</sub> = 0 to 5 V	–100 <sup>†</sup>		100	mV
V <sub>hys</sub> Hysteresis (V <sub>T+</sub> – V <sub>T–</sub> )			5		mV
V <sub>OH</sub> High-level output voltage	V <sub>ID</sub> = 100 mV, I <sub>OH</sub> = –1 mA	2.7	3.5		V
V <sub>OL</sub> Low-level output voltage	V <sub>ID</sub> = –100 mV, I <sub>OL</sub> = 16 mA		0.4	0.5	V
I <sub>OZ</sub> Off-state output current	V <sub>O</sub> = 2.4 V			–20	μA
I <sub>I</sub> Enable current	V <sub>I</sub> = 5.5 V			100	μA
I <sub>IH</sub> High-level enable current	V <sub>IH</sub> = 2.7 V			20	μA
I <sub>IL</sub> Low-level enable current	V <sub>IL</sub> = 0.4 V			–360	μA
r <sub>i</sub> Differential input resistance		4			kΩ
r <sub>o</sub> Output resistance				100	Ω
I <sub>OS</sub> Short-circuit output current		–15		–85	mA
I <sub>CC</sub> Supply current	V <sub>ID</sub> = 0, No load		17	20	mA

<sup>†</sup> The algebraic convention, where the more-negative limit is designated as minimum, is used in this data sheet for input threshold voltage levels only.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

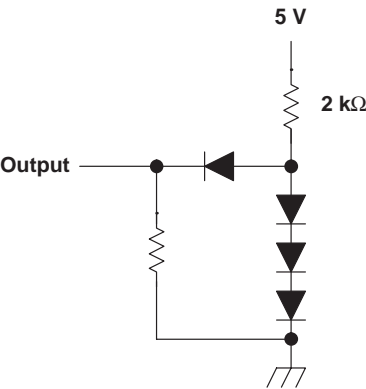
PARAMETER	TEST CONDITIONS	TYP	UNIT
t <sub>PLH</sub> Propagation delay time, low-to-high-level output	TTL load, See Note 5 and Figure 1	25	ns
t <sub>PHL</sub> Propagation delay time, high-to-low-level output		25	ns

NOTE 5: The response time specified is for a 100-mV input step with 5-mV overdrive (105 mV total) and is the interval between the input step function and the instant when the output crosses 2.5 V.

TL712  
DIFFERENTIAL COMPARATOR

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PARAMETER MEASUREMENT INFORMATION



NOTE A: All diodes are 1N4148 or equivalent.

Figure 1. TTL Output Load Circuit

TYPICAL CHARACTERISTICS

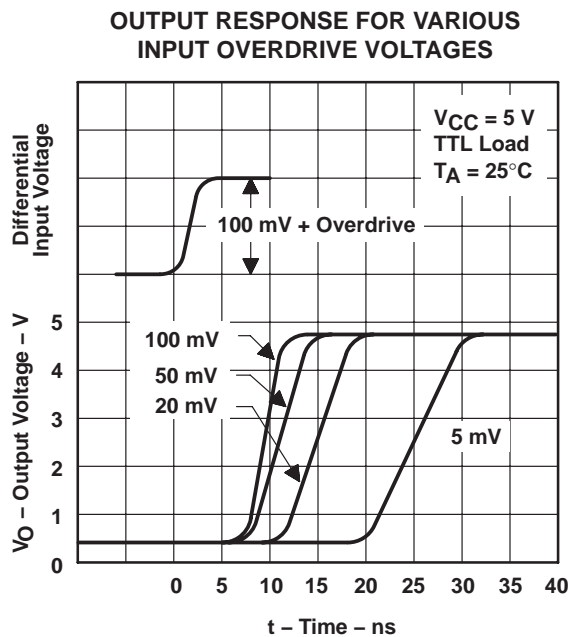


Figure 2

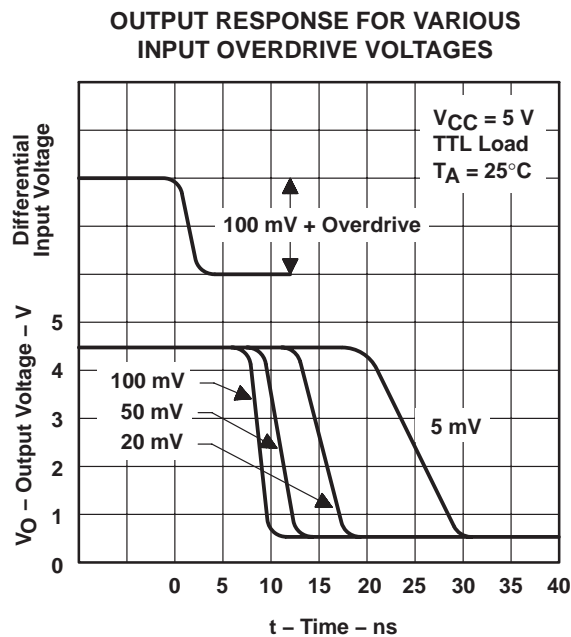


Figure 3

TYPICAL CHARACTERISTICS

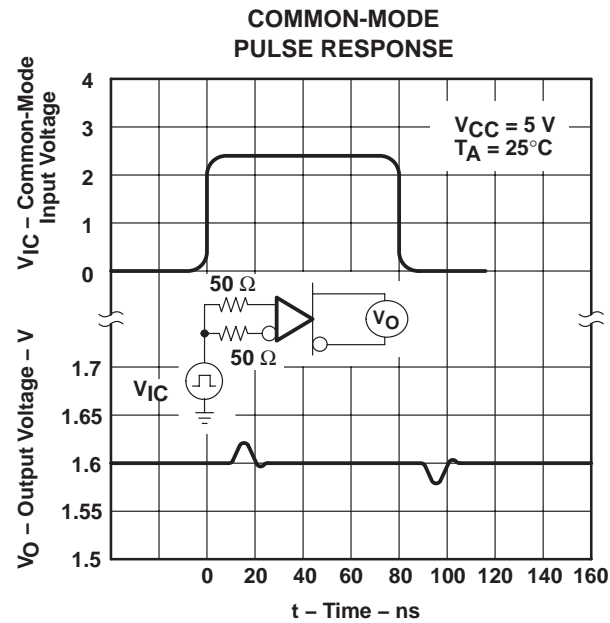


Figure 4

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL712CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL712CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL712CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL712CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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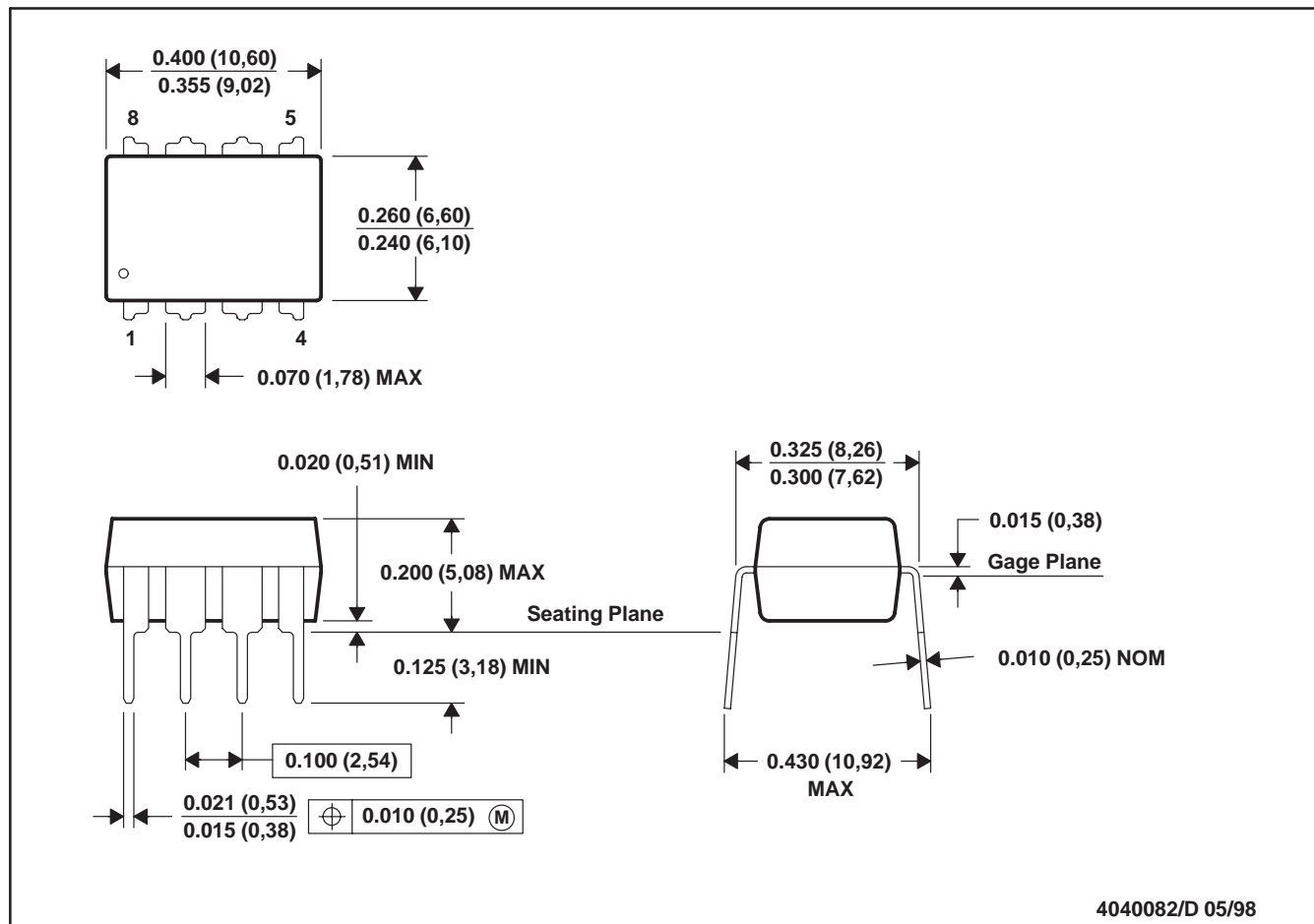
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# MECHANICAL DATA

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

## P (R-PDIP-T8)

## PLASTIC DUAL-IN-LINE

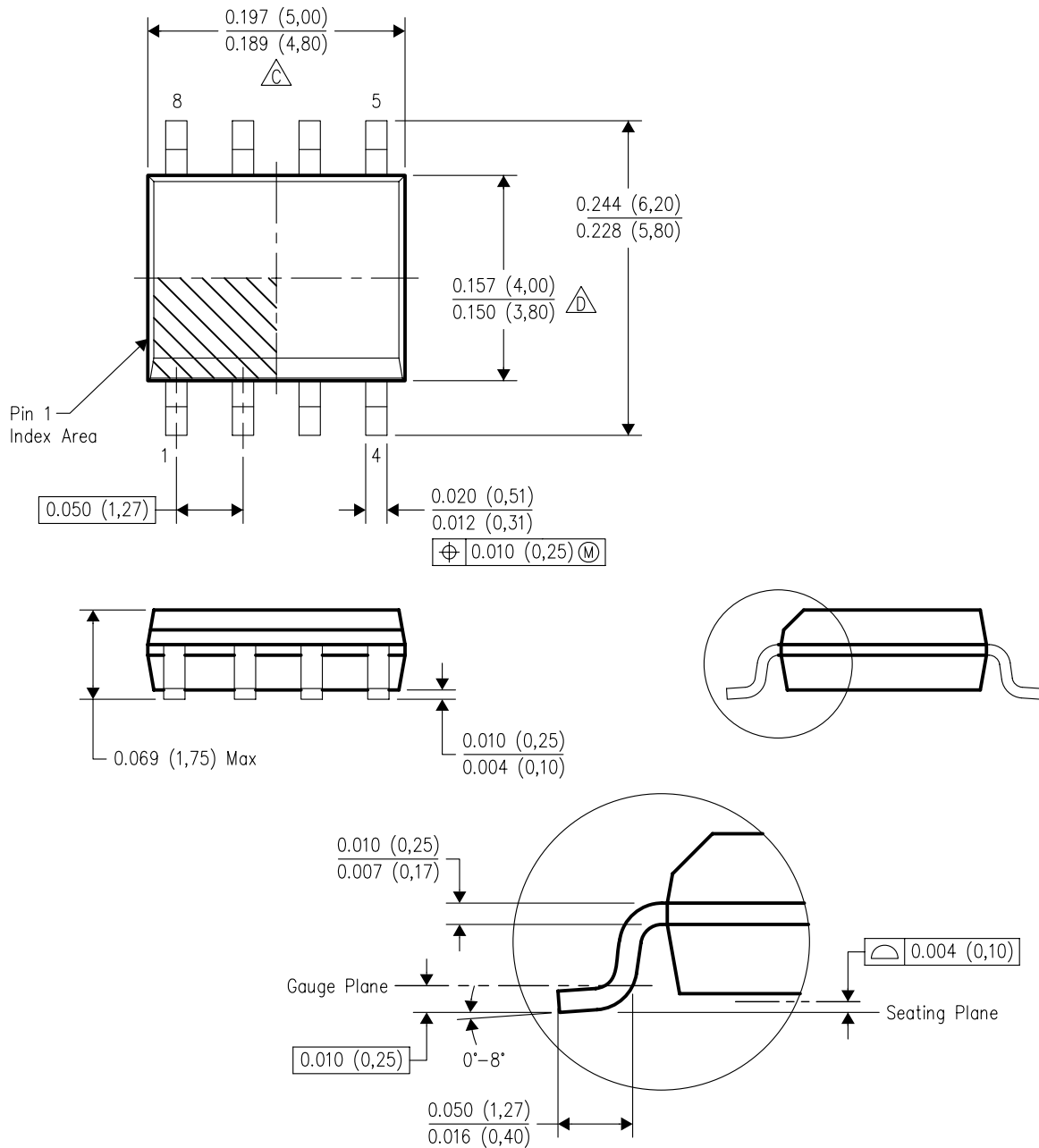


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001



## MECHANICAL DATA

D (R-PDSO-G8)

# PLASTIC SMALL-OUTLINE PACKAGE



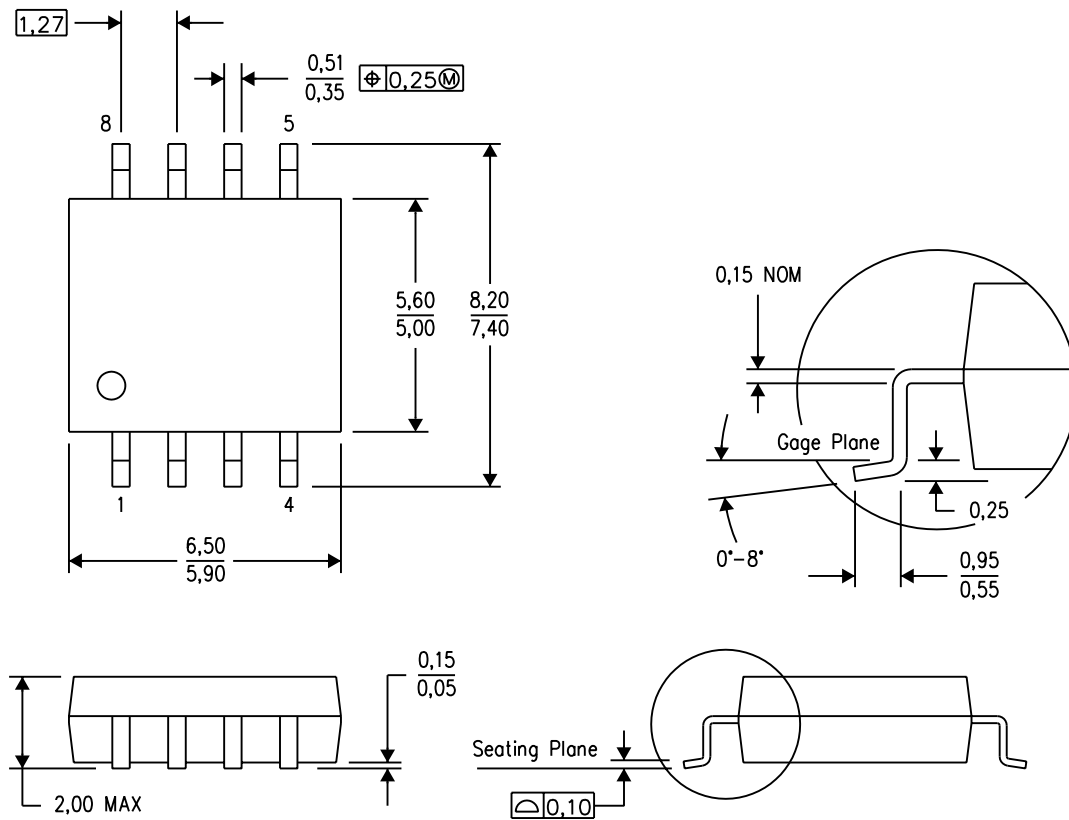
4040047-2/H 11/2006

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AA.

## MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4040063/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

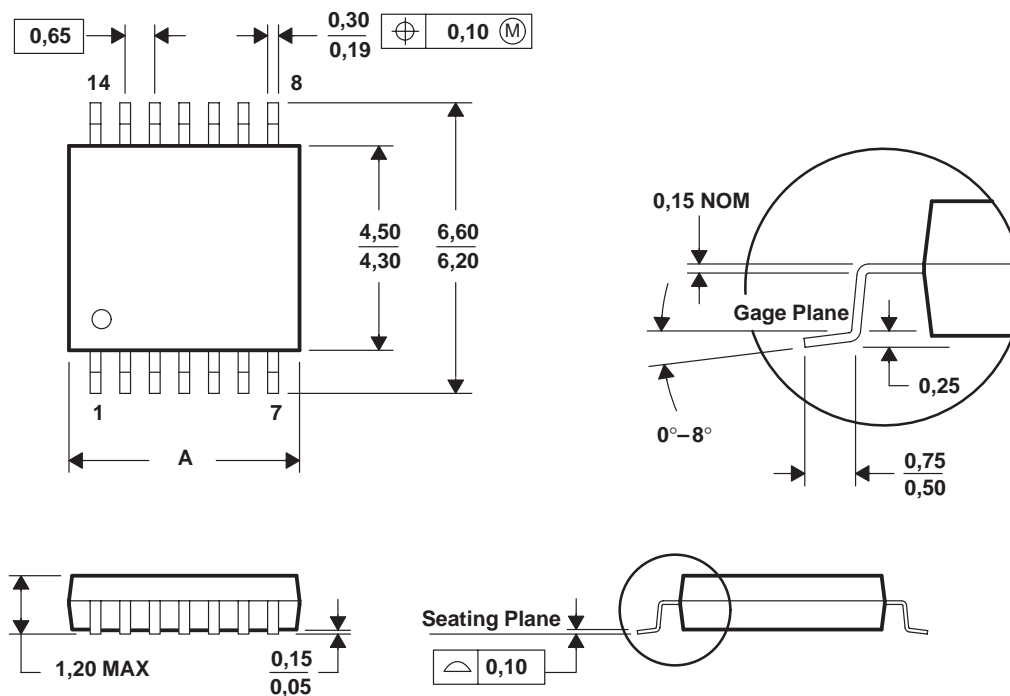
# MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



PINS ** DIM	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
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